

Solution !

Thermal Conductivity
5W/mK

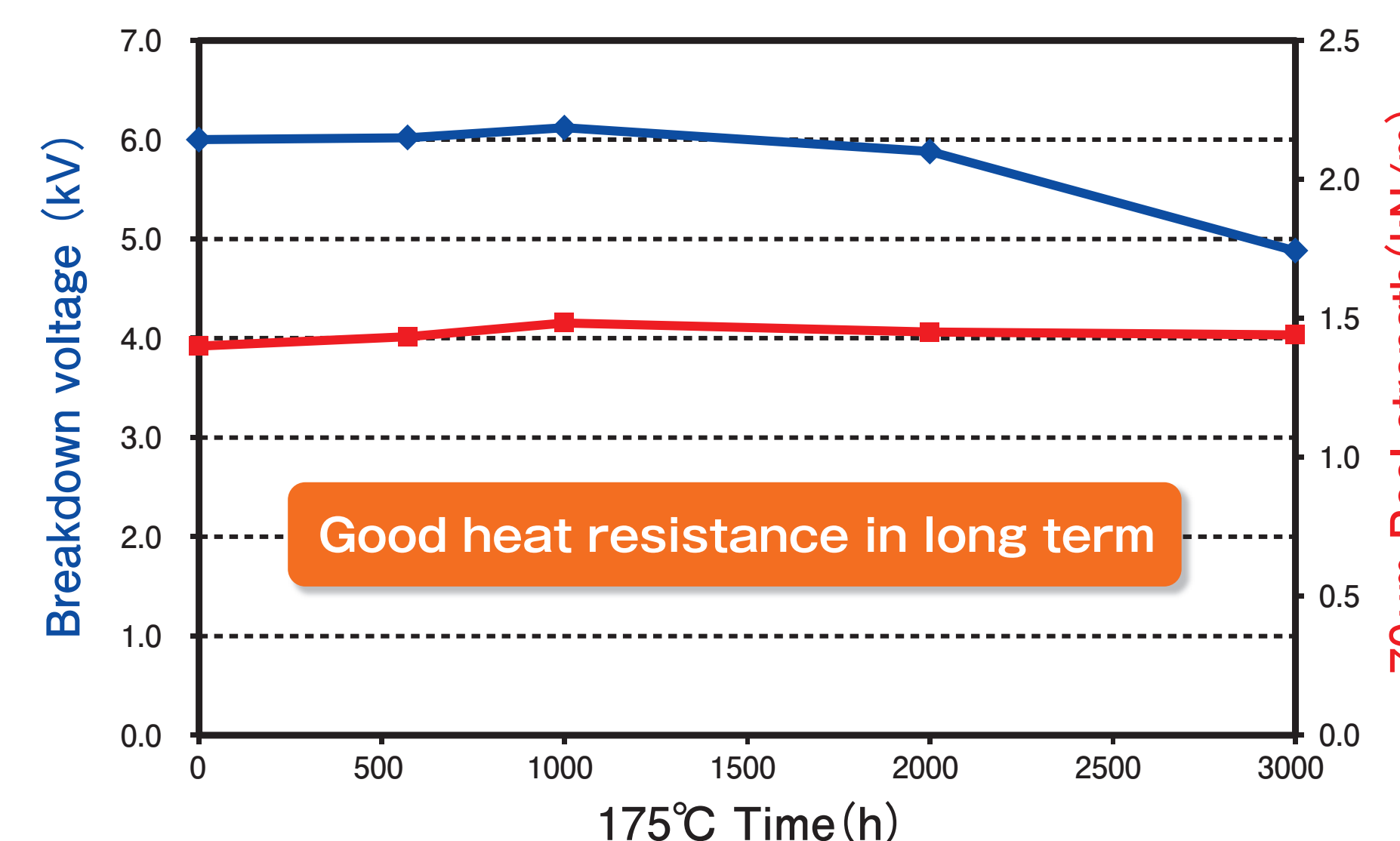
1 Metal PCB Material

- Thermal conductivity = **5W/mK** (Insulation layer)
- Bonding sheet is flexible and good handling property
- Suitable for various customer's needs : Bonding sheet, Aluminum-base CCL

Applications Substrate for High power LED, Inverter, Power module

AD-7200TY / AC-7200TY
Bonding sheet Aluminum-base CCL

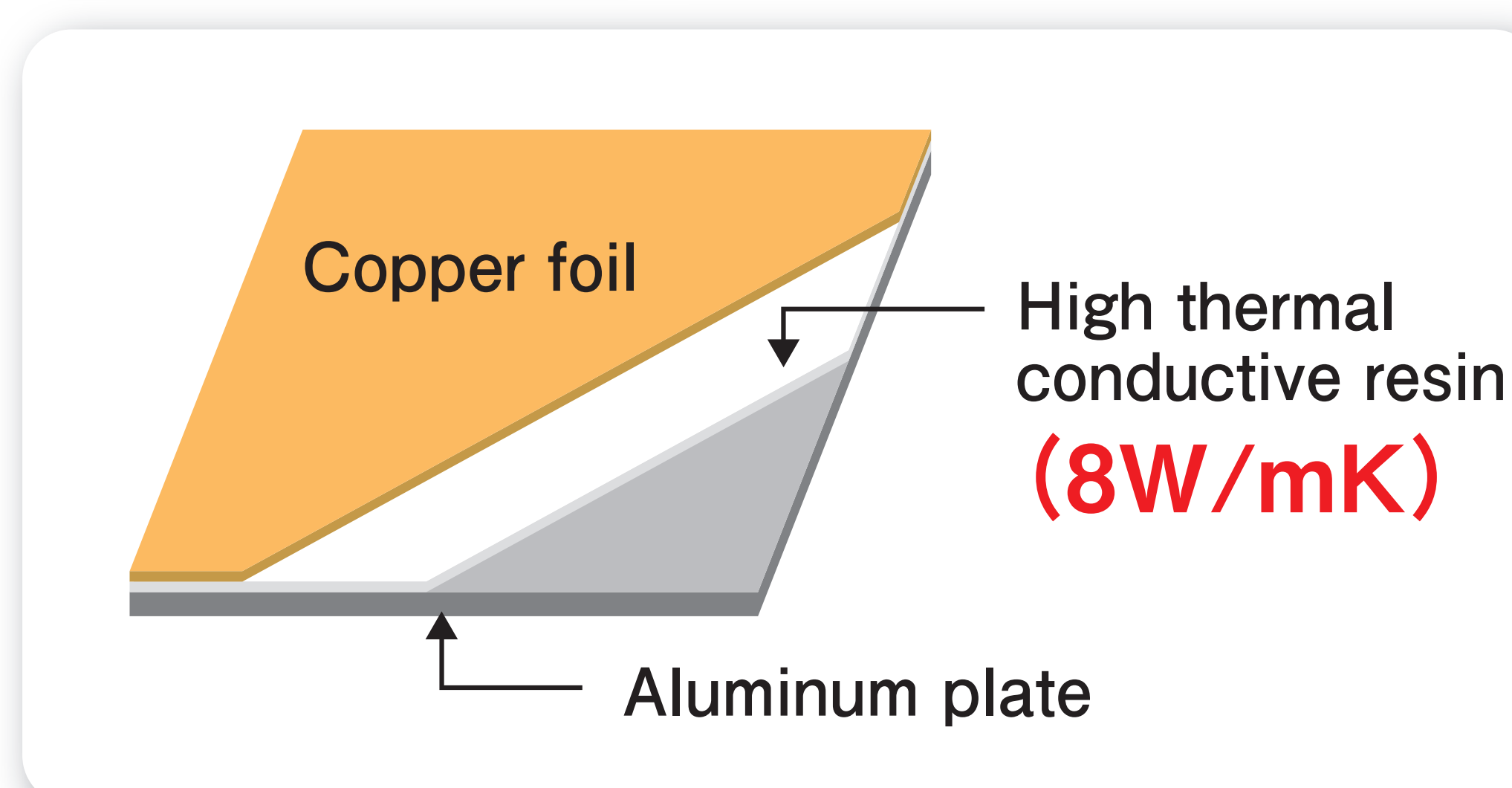
Long term reliability
(175°C)



Thermal Conductivity
8W/mK

2 High Thermal Conductive Metal PCB material

Composition



- High thermal conductivity = **8W/mK** (Insulation layer)
- High thermostability **Tg=270°C** (DMA)

Applications Substrate for High power LED, Power module

AC-7208 / CD-7208
Aluminum-base CCL Resin coated copper

NEW

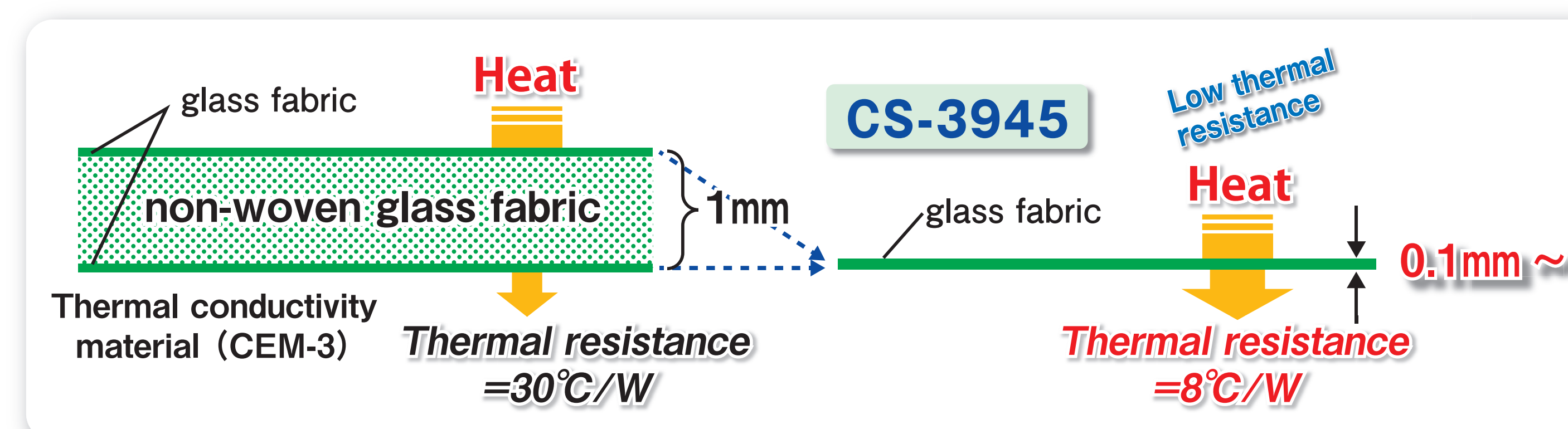
Test items	Unit	
Thermal conductivity	W/mK	8
Peel strength (Cu:35μm)	kN/m	1.2
Glass transition temperature Tg	°C	270
Coefficient of thermal expansion α1/α2	ppm/°C	9/22
Breakdown voltage (120μm)	kV	5.5

Thermal Conductivity
1.3W/mK

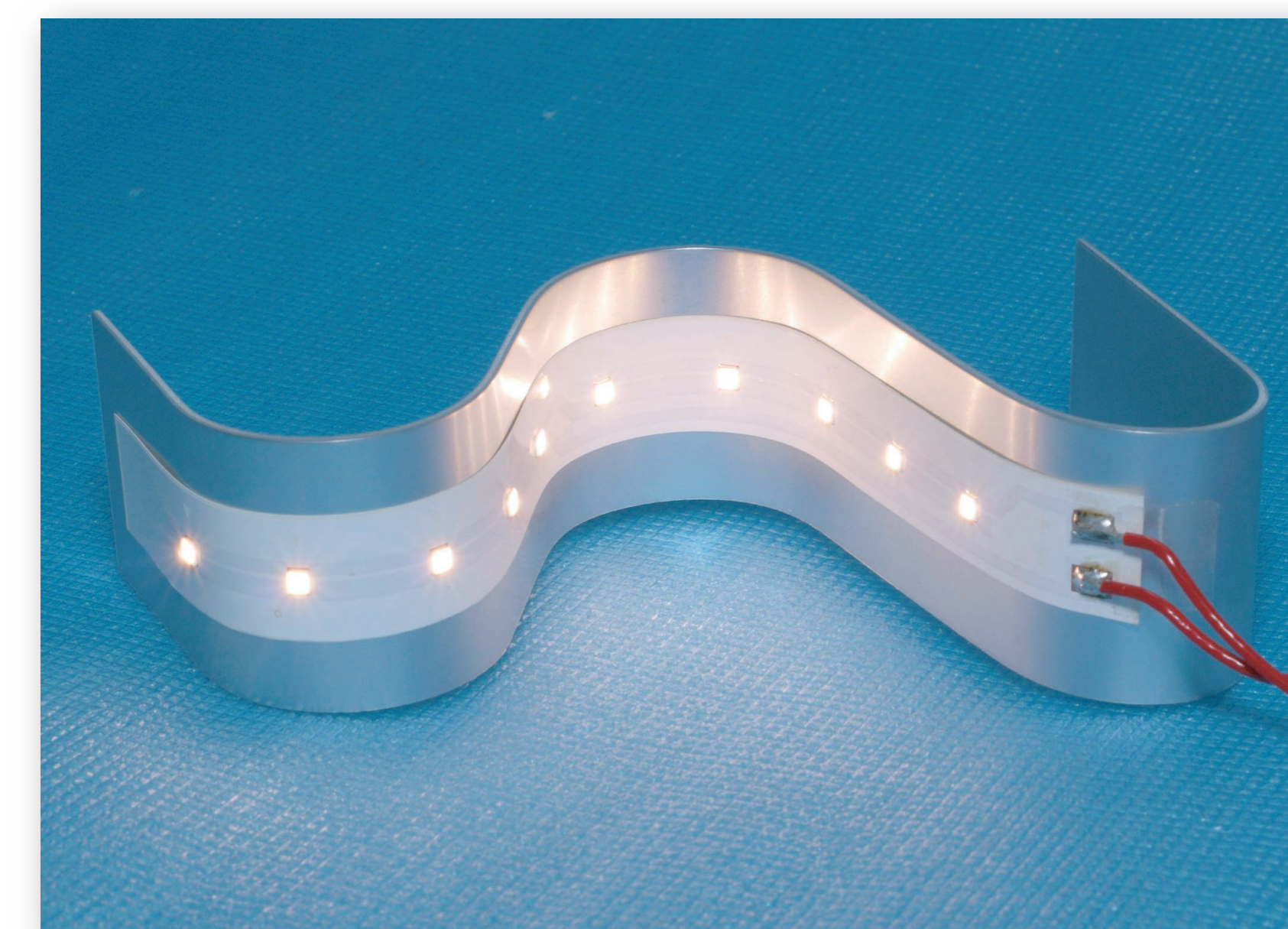
3 White Copper Clad Laminates

- Thermal Conductivity : **1.3W/mK**
- Minimum Thickness : **0.1mm**
- Advanced cooling design
- UL approved

Applications • LED lighting, LCD back-light, Automotive lamp (Daytime running lamp, Combination lamp, Clearance lamp)



CS-3945
Copper Clad Laminates



0.1mm thickness can be installed with curved shape design